

September 1983 Revised February 1999

MM74HC574 3-STATE Octal D-Type Edge-Triggered Flip-Flop

General Description

The MM74HC574 high speed octal D-type flip-flops utilize advanced silicon-gate P-well CMOS technology. They possess the high noise immunity and low power consumption of standard CMOS integrated circuits, as well as the ability to drive 15 LS-TTL loads. Due to the large output drive capability and the 3-STATE feature, these devices are ideally suited for interfacing with bus lines in a bus organized system.

These devices are positive edge triggered flip-flops. Data at the D inputs, meeting the set-up and hold time requirements, are transferred to the Q outputs on positive going transitions of the CLOCK (CK) input. When a high logic level is applied to the OUTPUT CONTROL (OC) input, all outputs go to a high impedance state, regardless of what

signals are present at the other inputs and the state of the storage elements.

The 74HC logic family is speed, function, and pinout compatible with the standard 74LS logic family. All inputs are protected from damage due to static discharge by internal diode clamps to V_{CC} and ground.

Features

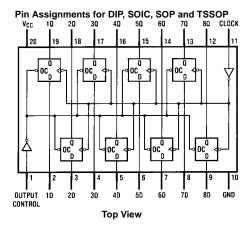
- Typical propagation delay: 18 ns
- Wide operating voltage range: 2V–6V
- Low input current: 1 µA maximum
- Low quiescent current: 80 µA maximum
- Compatible with bus-oriented systems
- Output drive capability: 15 LS-TTL loads

Ordering Code:

Order Number	Package Number	Package Description
MM74C574WM	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300"
MM74C574SJ	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
MM74C574MTC	MTC20	20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4m Wide
MM74C574N	N20A	20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

Connection Diagram



Truth Table

Output	Clock	Data	Output
Control			
L	1	Н	Н
L	1	L	L
L	L	Х	Q_0
Н	Х	Х	Z

- H = HIGH Level
- L = LOW Level
- X = Don't Care
- ↑ = Transition from LOW-to-HIGH
- Z = High Impedance State
- $\mathbf{Q}_0 = \mathsf{The}$ level of the output before steady state input conditions were established

Absolute Maximum Ratings(Note 1)

(Note 2)

Supply Voltage (V _{CC})	-0.5 to $+7.0$ V
DC Input Voltage (V _{IN})	-1.5 to $V_{CC} + 1.5V$
DC Output Voltage (V _{OUT})	-0.5 to V_{CC} +0.5 V
Clamp Diode Current (I _{IK} , I _{OK})	±20 mA
DC Output Current, per pin (I _{OUT})	±35 mA
DC V_{CC} or GND Current, per pin (I_{CC})	±70 mA
Storage Temperature Range (T _{STG})	-65°C to +150°C
Power Dissipation (P _D)	
(Note 3)	600 mW
S.O. Package only	500 mW
Lead Temperature (T _L)	
(Soldering 10 seconds)	260°C

Recommended Operating Conditions

	Min	Max	Units
Supply Voltage (V _{CC})	2	6	V
DC Input or Output Voltage	0	V_{CC}	V
(V_{IN}, V_{OUT})			
Operating Temperature Range (T _A)	-40	+85	°C
Input Rise or Fall Times			
(t_r, t_f) $V_{CC} = 2.0V$		1000	ns
$V_{CC} = 4.5V$		500	ns
$V_{CC} = 6.0V$		400	ns

Note 1: Maximum Ratings are those values beyond which damage to the device may occur.

Note 2: Unless otherwise specified all voltages are referenced to ground.

Note 3: Power Dissipation temperature derating — plastic "N" package: –
12 mW/°C from 65°C to 85°C.

DC Electrical Characteristics (Note 4)

Symbol	Parameter	Conditions	V _{CC}	$T_A = 25^{\circ}C$		T _A = -40 to 85°C	T _A = -55 to 125°C	Units
Syllibol	raiailletei	Conditions	•cc	Тур	Guaranteed Limits		imits	Ullits
V_{IH}	Minimum HIGH Level Input		2.0V		1.5	1.5	1.5	V
	Voltage		4.5V		3.15	3.15	3.15	V
			6.0V		4.2	4.2	4.2	V
V_{IL}	Maximum LOW Level Input		2.0V		0.5	0.5	0.5	٧
	Voltage		4.5V		1.35	1.35	1.35	V
i I			6.0V		1.8	1.8	1.8	V
V _{OH}	Minimum HIGH Level Output	$V_{IN} = V_{IH}$ or V_{IL}						
i I	Voltage	$ I_{OUT} \leq 20~\mu A$	2.0V	2.0	1.9	1.9	1.9	V
1			4.5V	4.5	4.4	4.4	4.4	V
i I			6.0V	6.0	5.9	5.9	5.9	V
		$V_{IN} = V_{IH}$ or V_{IL}						
		$ I_{OUT} \le 6.0 \text{ mA}$	4.5V	4.2	3.98	3.84	3.7	V
		$ I_{OUT} \le 7.8 \text{ mA}$	6.0V	5.7	5.48	5.34	5.2	V
V_{OL}	Maximum LOW Level Output	$V_{IN} = V_{IH}$ or V_{IL}						
	Voltage	$ I_{OUT} \leq 20~\mu A$	2.0V	0	0.1	0.1	0.1	V
1			4.5V	0	0.1	0.1	0.1	٧
			6.0V	0	0.1	0.1	0.1	V
1		$V_{IN} = V_{IH}$ or V_{IL}						
		$ I_{OUT} \le 6.0 \text{ mA}$	4.5V	0.2	0.26	0.33	0.4	V
1		$ I_{OUT} \le 7.8 \text{ mA}$	6.0V	0.2	0.26	0.33	0.4	٧
I _{IN}	Maximum Input Current	$V_{IN} = V_{CC}$ or GND	6.0V		±0.1	±1.0	±1.0	μΑ
I _{OZ}	Maximum 3-STATE	$V_{OUT} = V_{CC}$ or GND						
1	Output Leakage Current	$OC = V_{IH}$	6.0V		±0.5	±5.0	±10	μΑ
I _{CC}	Maximum Quiescent Supply	$V_{IN} = V_{CC}$ or GND						
	Current	$I_{OUT} = 0 \mu A$	6.0V		8.0	80	160	μΑ
ΔI_{CC}	Quiescent Supply Current	$V_{CC} = 5.5V$	OE	1.0	1.5	1.8	2.0	mA
i	per Input Pin	$V_{IN} = 2.4V$	CLK	0.6	0.8	1.0	1.1	mA
		or 0.4V (Note 4)	DATA	0.4	0.5	0.6	0.7	mA

Note 4: For a power supply of 5V \pm 10% the worst-case output voltages (V_{OH} , and V_{OL}) occur for HC at 4.5V. Thus the 4.5V values should be used when designing with this supply. Worst-case V_{IH} and V_{IL} occur at $V_{CC} = 5.5V$ and 4.5V respectively. (The V_{IH} value at 5.5V is 3.85V.) The worst-case leakage current (I_{IN} , I_{CC} , and I_{OZ}) occur for CMOS at the higher voltage and so the 6.0V values should be used.

AC Electrical Characteristics

 $V_{CC} = 5V$, $T_A = 25^{\circ}C$, $t_r = t_f = 6$ ns

Symbol	Parameter	Conditions	Тур	Guaranteed Limit	Units
f _{MAX}	Maximum Operating Frequency		60	33	MHz
t _{PHL} , t _{PLH}	Maximum Propagation Delay, Clock to Q	C _L = 45 pF	17	27	ns
t _{PZH} , t _{PZL}	Maximum Output Enable Time	$R_L = 1 \text{ k}\Omega$ $C_L = 45 \text{ pF}$	19	28	ns
t _{PHZ} , t _{PLZ}	Maximum Output Disable Time	$\begin{aligned} R_L &= 1 \ k\Omega \\ C_L &= 5 \ pF \end{aligned}$	14	25	ns
t _S	Minimum Setup Time, Data to Clock		10	12	ns
t _H	Minimum Hold Time, Clock to Data		-3	5	ns
t _W	Minimum Pulse Clock Width		8	15	ns

AC Electrical Characteristics

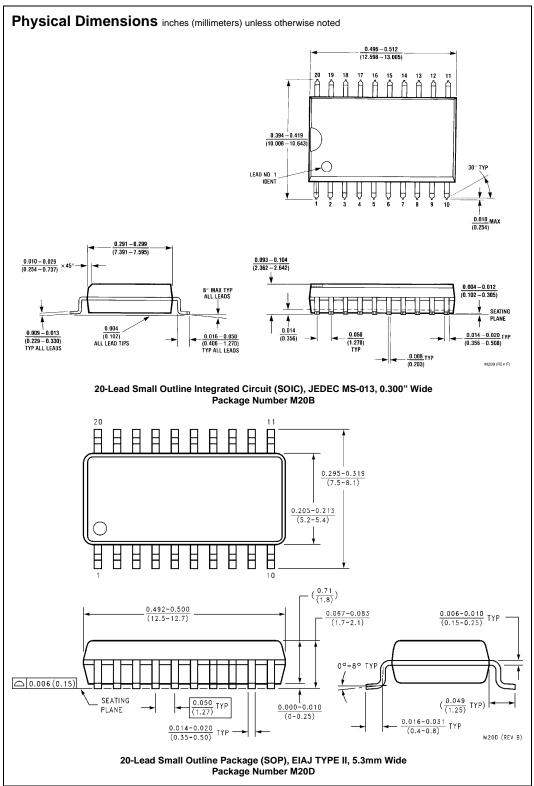
 $\rm V_{CC}\,{=}\,2.0\,{-}\,6.0\,\rm V,\,C_L\,{=}\,50$ pF, $\rm t_r\,{=}\,t_f\,{=}\,6$ ns (unless otherwise specified)

Symbol	Parameter	Conditions	v _{cc}	T _A = 25°C		$T_A = -40 \text{ to } 85^{\circ}\text{C}$ $T_A = -55 \text{ to } 125^{\circ}\text{C}$		Units
Jynnoon	Falailietei	Conditions		Тур		Guaranteed L	imits	Oilles
f _{MAX}	Maximum Operating Frequency	C _L = 50 pF	2.0V		33	28	23	MHz
			4.5V		30	24	20	MHz
			6.0V		35	28	23	MHz
t _{PHL} , t _{PLH}	Maximum Propagation	C _L = 50 pF	2.0V	18	30	38	45	ns
	Delay, Clock to Q	C _L = 150 pF	2.0V	51	155	194	233	ns
		C _L = 50 pF	4.5V	13	23	29	35	ns
		C _L = 150 pF	4.5V	19	31	47	47	ns
		C _L = 50 pF	6.0V	12	20	25	30	ns
		C _L = 150 pF	6.0V	18	27	34	41	ns
t _{PZH} , t _{PZL}	Maximum Output Enable	$R_L = 1 k\Omega$						
	Time	$C_L = 50 pF$	2.0V	22	30	38	45	ns
		C _L = 150 pF	2.0V	59	180	225	270	ns
		C _L = 50 pF	4.5V	14	28	35	42	ns
		C _L = 150 pF	4.5V	20	36	45	54	ns
		C _L = 50 pF	6.0V	12	24	30	36	ns
		C _L = 150 pF	6.0V	18	31	39	47	ns
t _{PHZ} , t _{PLZ}	Maximum Output Disable Time	$R_L = 1 k\Omega$	2.0V	15	30	38	45	ns
		C _L = 50 pF	4.5V	12	25	31	38	ns
			6.0V	10	21	27	32	ns
t _S	Minimum Setup Time		2.0V	6	12	15	18	ns
	Data to Clock		4.5V		20	25	30	ns
			6.0V		17	21	25	ns
t _H	Minimum Hold Time		2.0V	-1	5	6	8	ns
	Clock to Data		4.5V		0	0	0	ns
			6.0V		0	0	0	ns
t _{THL} , t _{TLH}	Maximum Output Rise	C _L = 50 pF	2.0V	6	12	15	18	ns
	and Fall Time		4.5V	7	12	15	18	ns
			6.0V	6	10	13	15	ns
t _W	Minimum Clock Pulse Width		2.0V	30	15	20	24	ns
			4.5V	9	16	20	24	ns
			6.0V	8	14	18	20	ns
t _r ,t _f	Maximum Clock Input Rise	İ	2.0V		1000	1000	1000	ns
	and Fall Time		4.5V		500	500	500	ns
			6.0V		400	400	400	ns
C _{PD}	Power Dissipation Capacitance	OC = VCC		5				pF
	(Note 5) (per latch)	OC = GND		58				pF
C _{IN}	Maximum Input Capacitance	İ		5	10	10	10	pF

AC Electrical Characteristics (Continued)

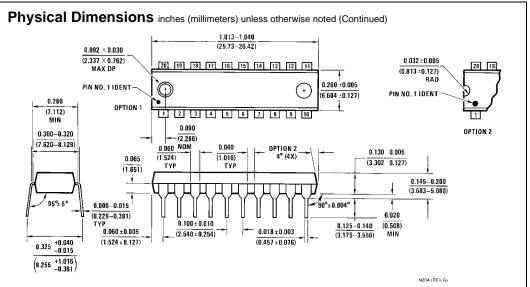
Symbol	Parameter	Conditions	v _{cc}	T _A = 25°C		$T_A = -40 \text{ to } 85^{\circ}\text{C}$ $T_A = -55 \text{ to } 125^{\circ}\text{C}$		Units
Cy	i didinoto.	00.14.1.0.10	00	Тур	Guaranteed Limits			
C _{OUT}	Maximum Output			15	20	20	20	pF
	Capacitance							

Note 5: C_{PD} determines the no load dynamic power consumption, $P_D = C_{PD} \ V_{CC}^2 \ f + I_{CC} \ V_{CC}$, and the no load dynamic current consumption, $I_S = C_{PD} \ V_{CC} \ f + I_{CC}$.



Physical Dimensions inches (millimeters) unless otherwise noted (Continued) -0.20 و2ا 7.72 4.16 6,4 4.4±0.1 -B-3,2 10.42 PIN #1 IDENT. LAND PATTERN RECOMMENDATION O.1 C SEE DETAIL A -0.90+0.15 0.09-0.20 0.1±0.05 0.65 0.19-0.30 | \$\P\$ | 0.10\P\$ | A| P\$ | C\$ | -12.00° R0.09min GAGE PLANE DIMENSIONS ARE IN MILLIMETERS NOTES: 0.25 SEATING PLANE A. CONFORMS TO JEDEC REGISTRATION MID-153, VARIATION AC, REF NOTE 6, DATE $7/93.\,$ -0.6±0.1-R0.09mln -1.00 B. DIMENSIONS ARE IN MILLIMETERS. C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLDS FLASH, AND TIE BAR EXTRUSIONS. DETAIL A D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.

20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide Package Number MTC20



20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide Package Number N20A

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